TMN6010D

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

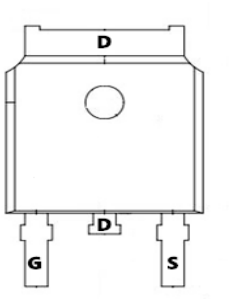
- Load switch
- PWM

General Features

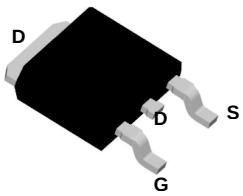
V_{DS} =60V I_D =10 A

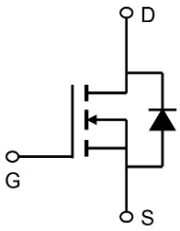
$R_{DS(ON)}$ = 65 mΩ (typ.) @ V_{GS} =-10V

100% UIS Tested
100% R_g Tested



TO-252-3L





Marking : 10N06

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	±20	V
Drain Current	T_A=25℃	I_D	10	A
	T_A=100℃		8	
Pulsed Drain Current [A]		I_{DM}	18	A
Total Power Dissipation [B]	T_A=25℃	P_D	1.2	W
	T_A=100℃		0.45	
Junction and Storage Temperature Range		T_J ,T_{STG}	-55～+150	℃

Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient [C]	Steady-State	$R_{\theta JA}$	85	105	℃/W

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Electrical Characteristics (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}= 0V, I_D=250μA	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V, V_{GS}=0V	-	-	1	μA
		V_{DS}=60V, V_{GS}=0V, Tj=150℃	-	-	100	
Gate-Body Leakage Current	I_{GSS}	V_{GS}= ±20V, V_{DS}=0V	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS}, I_D=250μA	0.9	1.35	2	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=3A	-	65	82	mΩ
		V_{GS}=4.5V, I_D=3A	-	75	92	
Diode Forward Voltage	V_{SD}	I_S=3A, V_{GS}=0V	-	0.85	1.2	V
Gate resistance	R_G	f=1MHz, Open drain	-	2	-	Ω
Maximum Body-Diode Continuous Current	I_S		-	-	10	A
Dynamic Parameters						
Input Capacitance	C_{iss}	V_{DS}=30V, V_{GS}=0V, f=1MHz	-	500	-	pF
Output Capacitance	C_{oss}		-	28	-	
Reverse Transfer Capacitance	C_{rss}		-	22	-	
Switching Parameters						
Total Gate Charge	Q_g	V_{GS}=10V, V_{DS}=30V, I_D=3A	-	10	-	nC
Gate-Source Charge	Q_{gs}		-	1.7	-	
Gate-Drain Charge	Q_{gd}		-	2.1	-	
Reverse Recovery Charge	Q_{rr}	I_F=3A, di/dt=100A/us	-	7	-	nC
Reverse Recovery Time	t_{rr}		-	33	-	ns
Turn-on Delay Time	$t_{D(on)}$	V_{GS}=10V, V_{DD}=30V, R_L=20Ω R_{GEN}=3Ω	-	3.6	-	ns
Turn-on Rise Time	t_r		-	17.6	-	
Turn-off Delay Time	$t_{D(off)}$		-	13	-	
Turn-off fall Time	t_f		-	23	-	

A. Repetitive rating; pulse width limited by max. junction temperature.
B. P_d is based on max. junction temperature, using junction-case thermal resistance.
C. The value of $R_{\theta JA}$ is measured with the device mounted on the minimum recommend pad size, in the still air environment with T_A =25℃. The maximum allowed junction temperature of 150℃. The value in any given application depends on the user's specific board design.

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Typical Electrical and Thermal Characteristics Diagrams

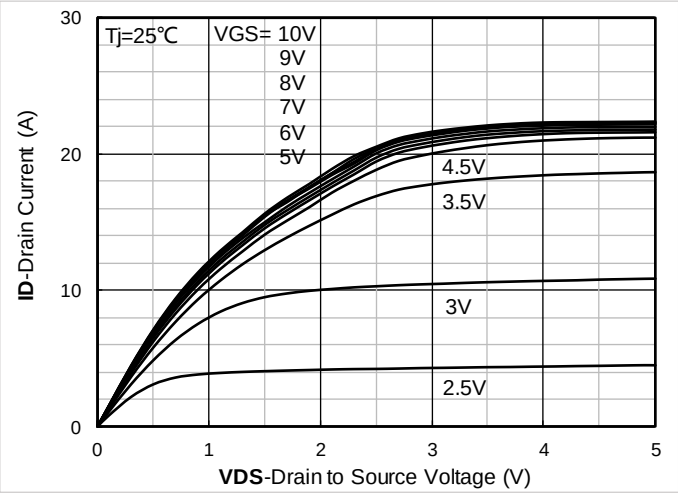


Figure 1. Output Characteristics

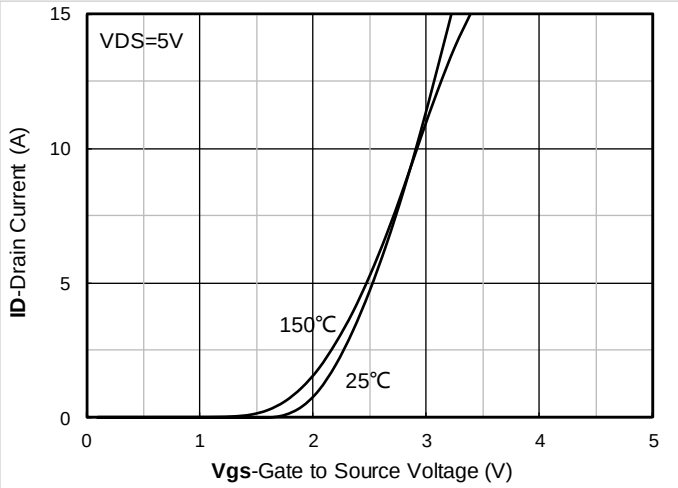


Figure 2. Transfer Characteristics

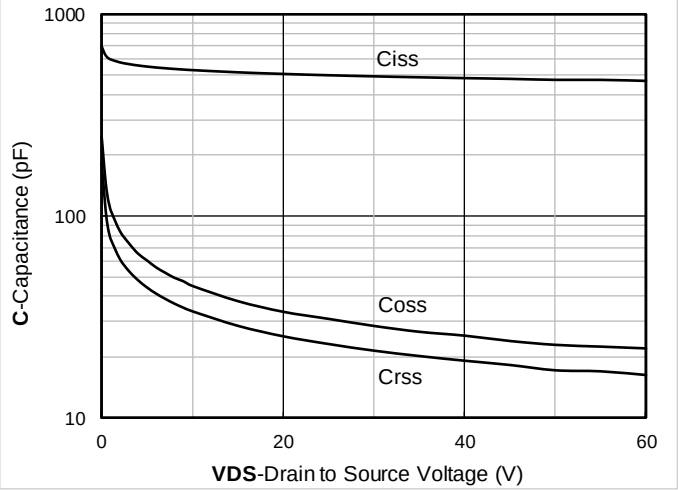


Figure 3. Capacitance Characteristics

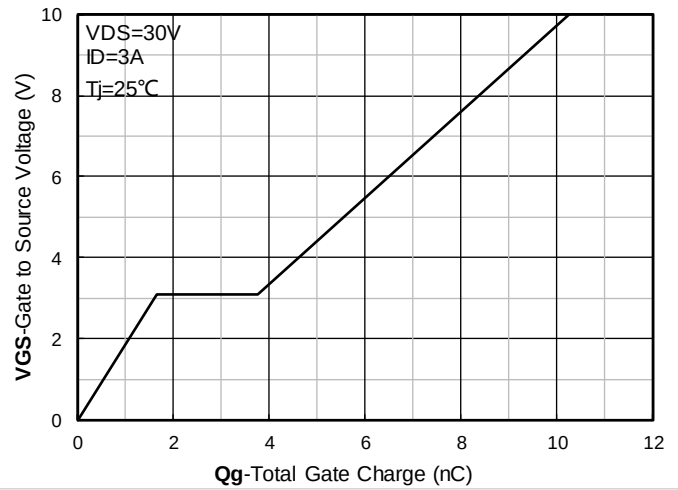


Figure 4. Gate Charge

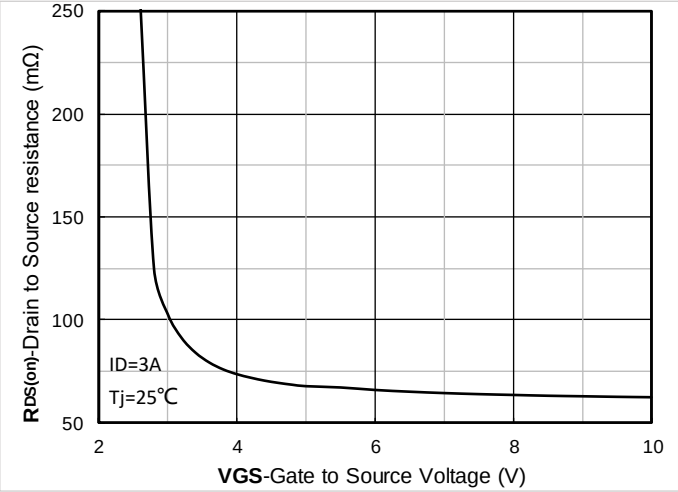


Figure 5. On-Resistance vs Gate to Source Voltage

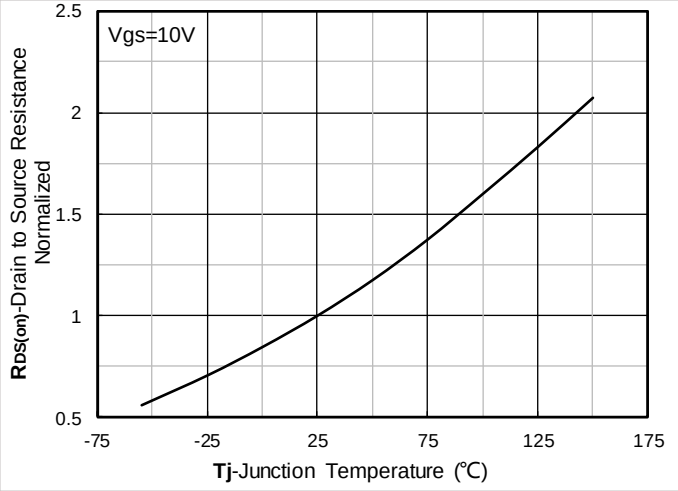


Figure 6. Normalized On-Resistance

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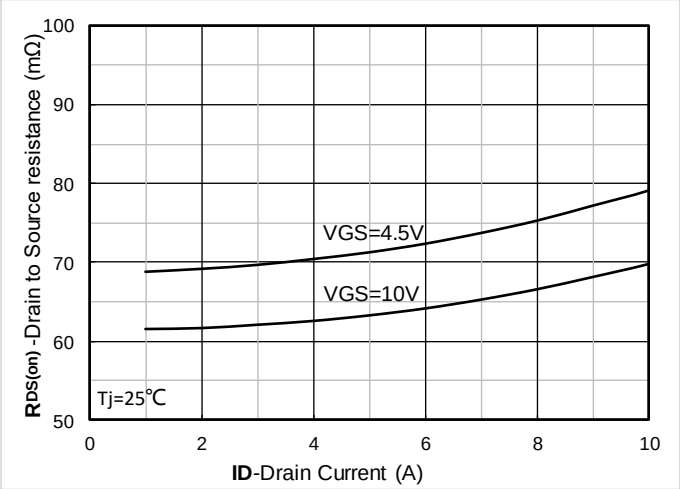


Figure 7. RDS(on) VS Drain Current

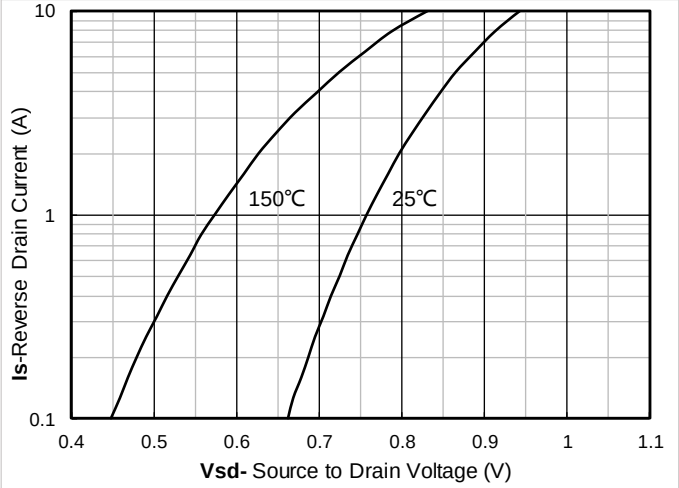


Figure 8. Forward characteristics of reverse diode

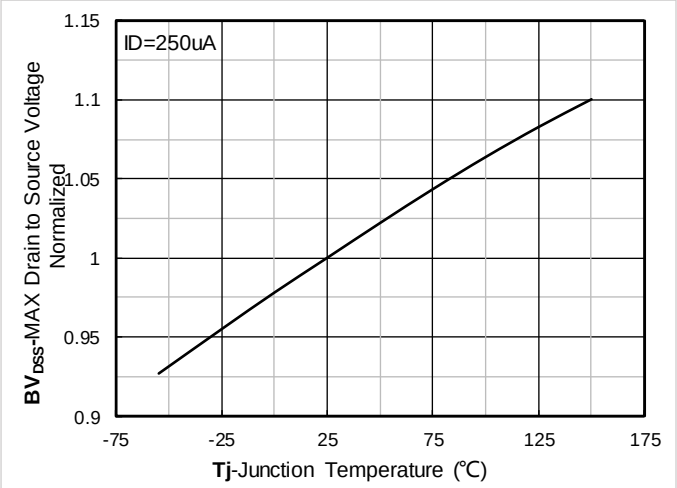


Figure 9. Normalized breakdown voltage

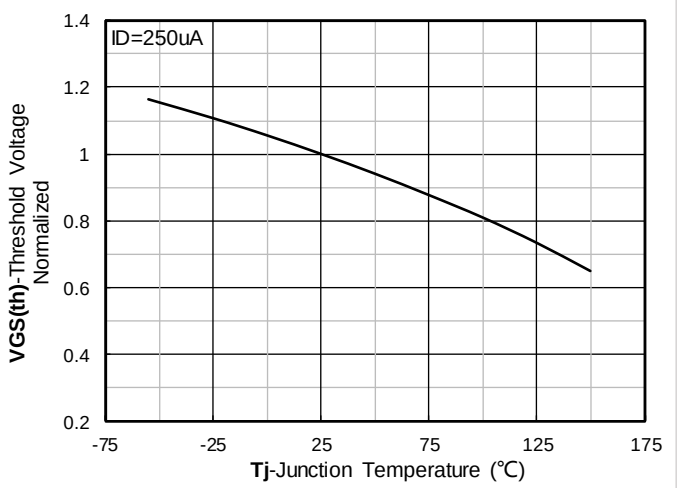


Figure 10. Normalized Threshold voltage

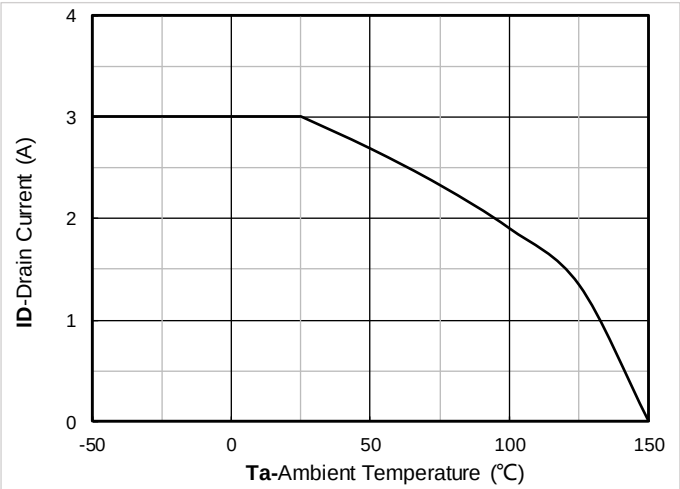


Figure 11. Current dissipation

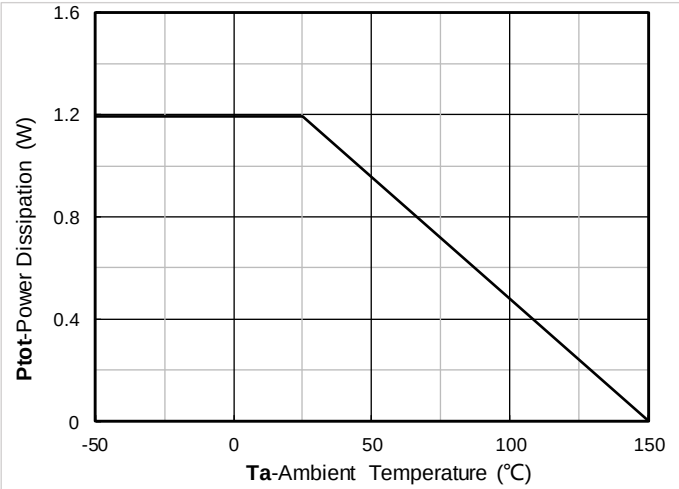


Figure 12. Power dissipation

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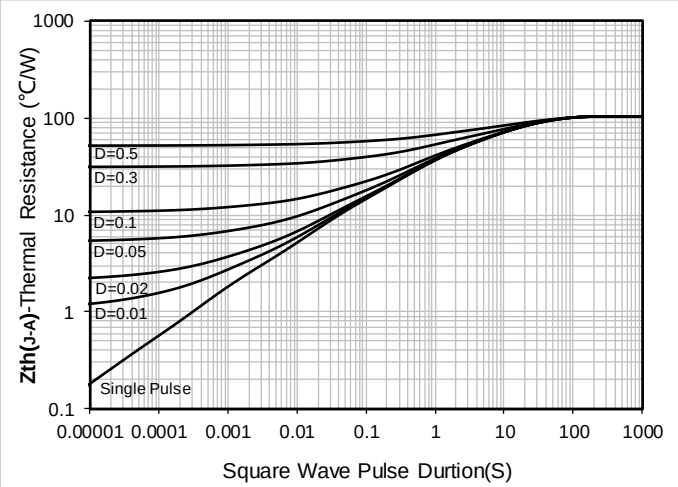


Figure 13. Maximum Transient Thermal Impedance

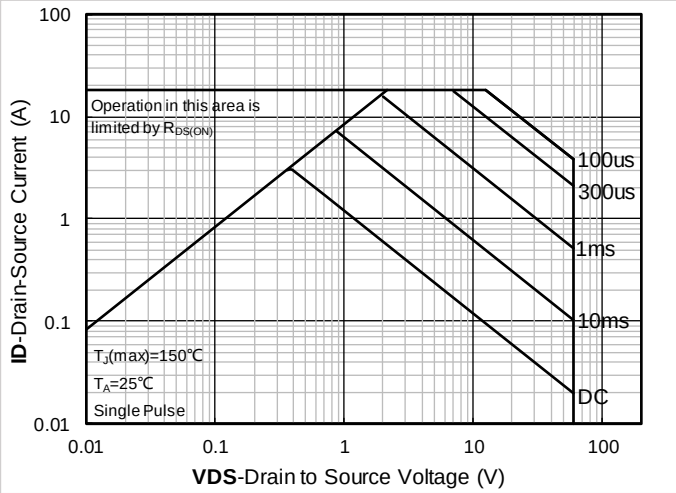


Figure 14. Safe Operation Area

Test Circuits & Waveforms

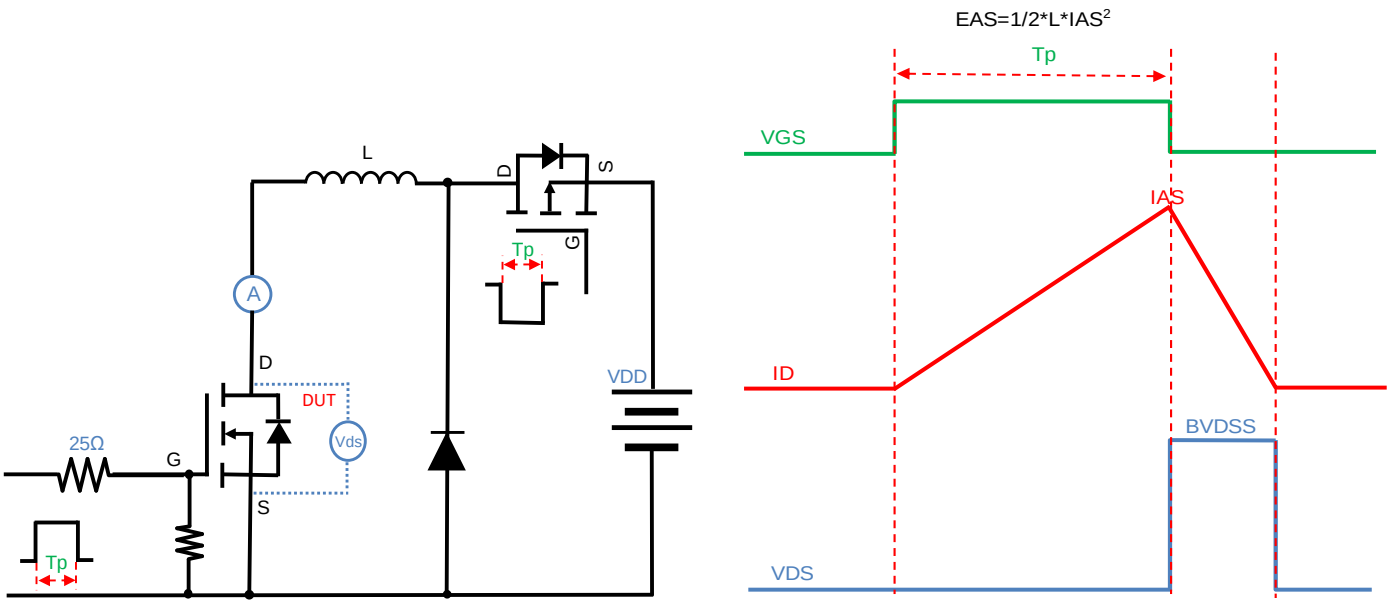


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

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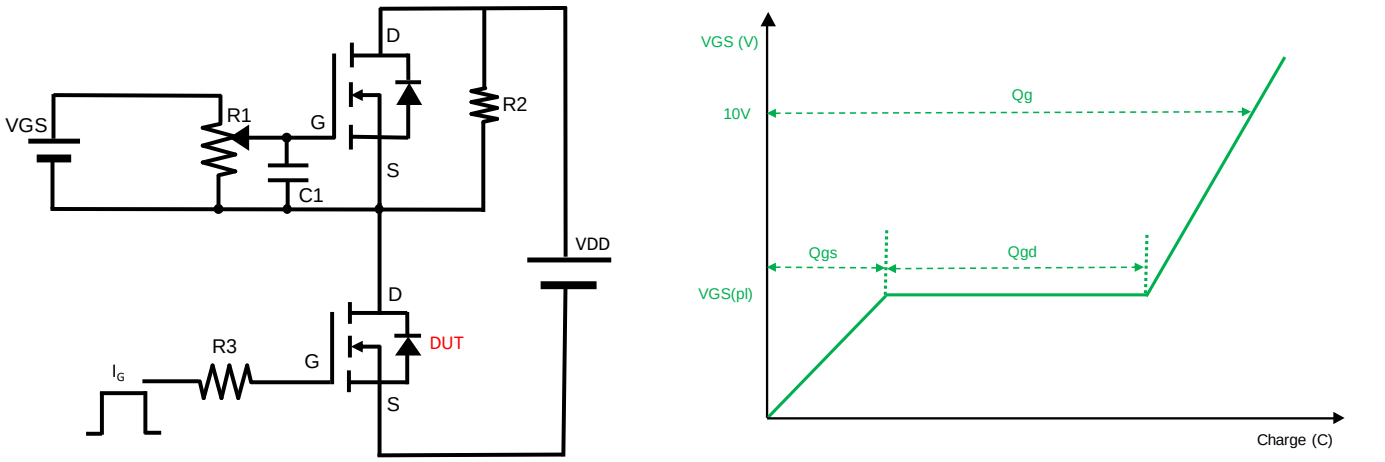


Figure B. Gate Charge Test Circuit & Waveform

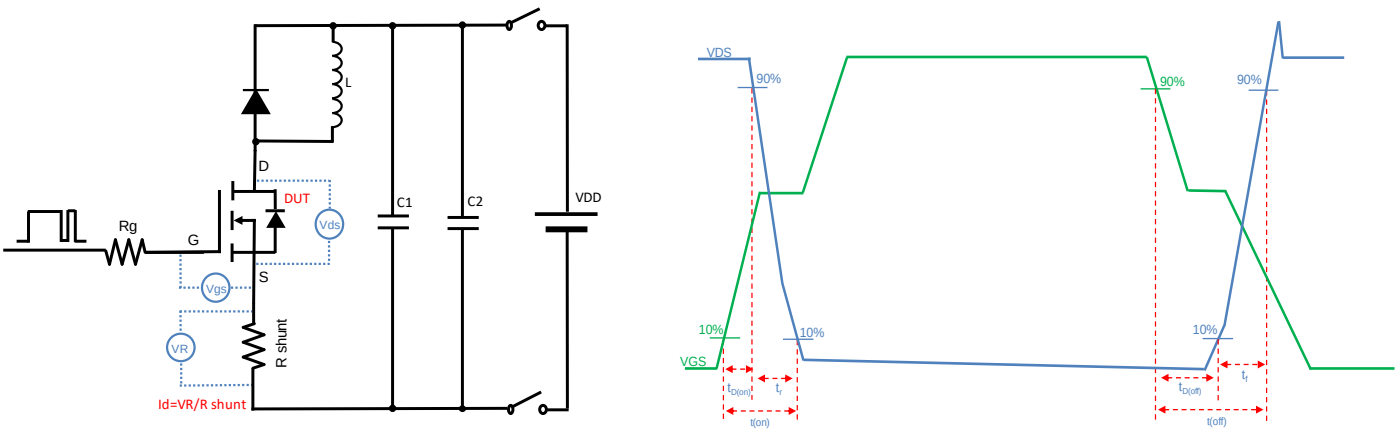


Figure C. Resistive Switching Test Circuit & Waveform

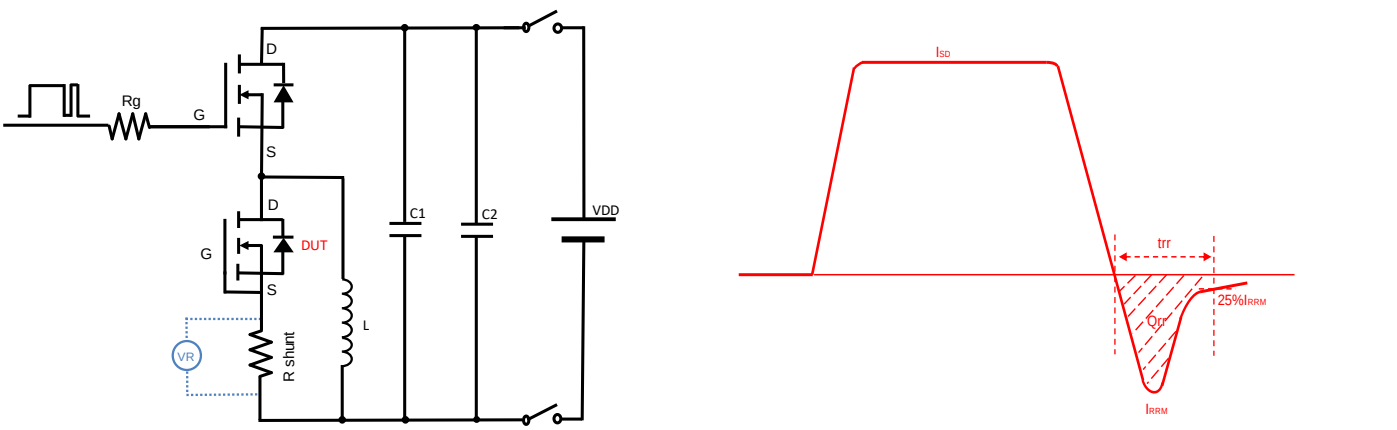
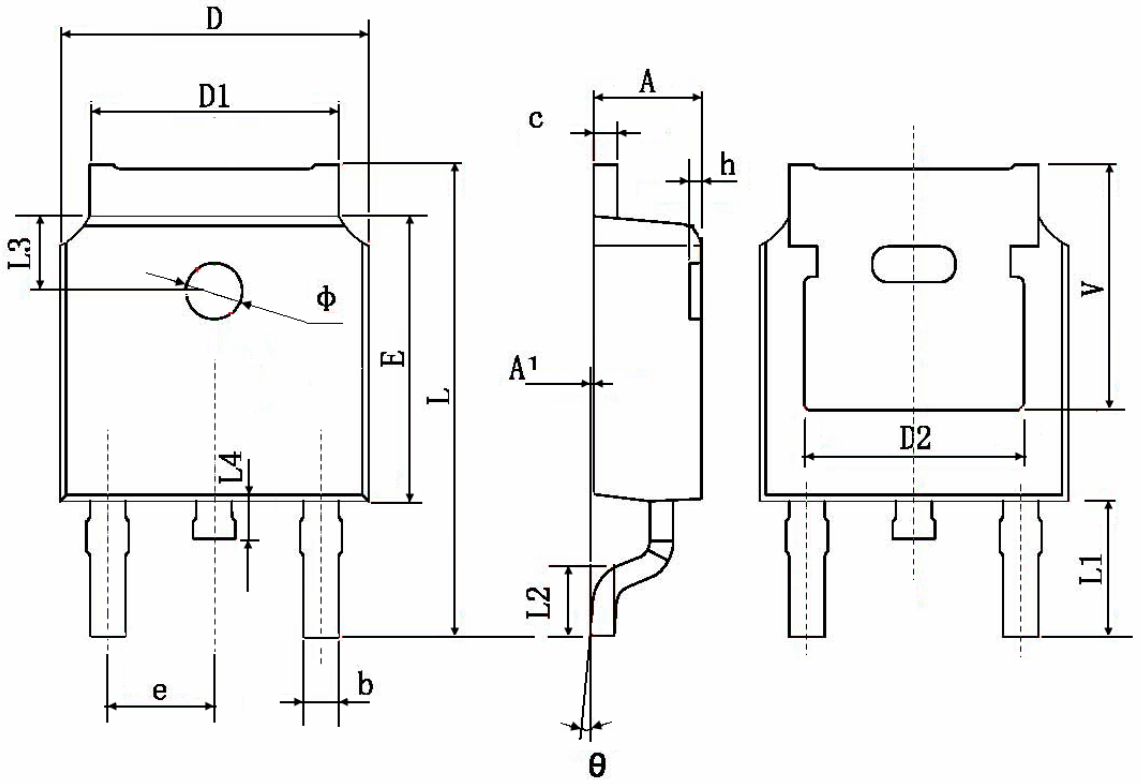


Figure D. Diode Recovery Test Circuit & Waveform

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Package Information:TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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